

xRSB-50T05, xRSB-50T12

Isolated DC-DC Converter

The xRSB-50T series are isolated DC-DC converters that operate from a nominal 48 VDC source. These units will provide up to 60 W of output power from a nominal 48 VDC input. These units are designed to be highly efficient and low cost.

Features include remote on/off, over current protection and under voltage lockout. These converters are provided in an industry standard sixteenth brick package.



Key Features & Benefits

- 48 VDC Input
- 5 VDC @12 A, 12 VDC @ 5 A Output
- 1/16th Brick Converter
- Isolated
- Fixed Frequency (600 kHz)
- High Efficiency
- High Power Density
- Low Cost
- Input Under Voltage Lockout
- Output Voltage Trim
- Output Over Voltage Shutdown
- OCP/SCP
- Over Temperature Protection
- Remote On/Off
- Basic Insulation
- Positive/Negative remote sense
- Through Hole and SMT (option)
- Approved to UL/CSA 62368-1
- Approved to IEC/EN 62368-1
- Class II, Category 2, Non-Isolated DC-DC Converter (refer to IPC-9592B)

Applications

- Networking
- Computers and Peripherals
- Telecommunications

1. MODEL SELECTION

MODEL NUMBER	MODEL NUMBER	OUTPUT VOLTAGE	INPUT VOLTAGE	MAX. OUTPUT CURRENT	MAX. OUTPUT POWER	TYPICAL EFFICIENCY
0RSB-50T05L	0RSB-50T050	5.0 V	36 V - 75 V	12 A	60 W	90%
SRSB-50T05L	SRSB-50T050					
0RSB-50T12L	0RSB-50T120	12 V	36 V - 75 V	5 A	60 W	89%
SRSB-50T12L	SRSB-50T120					

NOTE: 1. Add “G” or “H” suffix at the end of the model number to indicate tray packaging.

2. Add “R” or “S” suffix at the end of SRSB-50Txxx to indicate tape and reel packaging.

PART NUMBER EXPLANATION

x	R	SB	-	50	T	xx	x	y
Mounting Type	RoHS Status	Series Name		Series code	Input Range	Output Voltage	Active Logic	Package Type
0 - Through hole mount	RoHS	1/16 th Brick	-	36 – 75 V	05 – 5 V	0 – Active High	L – Active Low	G/H – Tray package
S – Surface mount								R/S – Tape and Reel package

2. ABSOLUTE MAXIMUM RATINGS

PARAMETER	DESCRIPTION	MIN	TYP	MAX	UNIT
Continuous non-operating Input Voltage		-0.3	-	80	V
Input Transient Voltage	100 ms maximum	-0.3	-	100	V
Remote On/Off		-0.3	-	18	V
I/O Isolation Voltage		-	-	1500	V
Ambient Temperature		-40	-	85	°C
Storage Temperature		-55	-	125	°C
Altitude		-	-	2000	m

NOTE: Ratings used beyond the maximum ratings may cause a reliability degradation of the converter or may permanently damage the device.

3. INPUT SPECIFICATIONS

All specifications are typical at 25°C unless otherwise stated.

PARAMETER	DESCRIPTION	MIN	TYP	MAX	UNIT
Operating Input Voltage		36	48	75	V
Input Current (full load)		-	-	2.4	A
Input Current (no load)		-	70	120	mA
Remote Off Input Current		-	1	3	mA
Input Reflected Ripple Current (rms)	Tested with simulated source impedance of 15 μ H, 5 Hz to 20 MHz; use a 100 μ F/100 V electrolytic capacitor with ESR=1 ohm max at 200 kHz at the input.	-	3	7	mA
Input Reflected Ripple Current (pk-pk)		-	20	50	mA
I ² t Inrush Current Transient		-	0.01	0.02	A ² s
Turn-on Voltage Threshold		31	32	35	V
Turn-off Voltage Threshold		30	31	34	V

NOTES: All specifications are typical at 25 °C unless otherwise stated.

4. OUTPUT SPECIFICATIONS

All specifications are typical at nominal input, full load at 25°C unless otherwise stated.

PARAMETER		DESCRIPTION	MIN	TYP	MAX	UNIT	
Output Voltage Set Point	Vo = 5.0 V	Test conditions: Vin = 48 V; Io = 50% load	4.925	5.0	5.075	V	
	Vo = 12 V		11.750	12.0	12.250	V	
Load Regulation	Vo = 5.0 V		-	±4	±9	mV	
	Vo = 12 V		-	±10	±25	mV	
Line Regulation	Vo = 5.0 V		-	±4	±9	mV	
	Vo = 12 V		-	±9	±18	mV	
Regulation Over Temperature	Vo = 5.0 V		-	±15	±30	mV	
	Vo = 12 V		-	±20	±35	mV	
Output Current	Vo = 5.0 V		0	-	12	A	
	Vo = 12 V		0	-	5	A	
Current Limit Threshold	Vo = 5.0 V		14	19	24	A	
	Vo = 12 V		5.2	6.5	8.5	A	
Short Circuit Surge Transient			-	0.5	1	A2s	
Ripple and Noise (rms)	Vo = 5.0 V	Tested at 0-20 MHz BW, with a 1 µF ceramic capacitor and a Tantalum capacitor (refer to the min. output capacitance below for each output) at the output.	-	25	50	mV	
	Vo = 12 V		-	30	55	mV	
Ripple and Noise (pk-pk)	Vo = 5.0 V		-	70	120	mV	
	Vo = 12 V		-	90	180	mV	
Turn on Time			-	35	70	ms	
Overshoot at Turn on			-	0	5	%	
Output Capacitance	Vo = 5.0 V	Recommend using AVX TPS series Tantalum capacitor as the min capacitor	100	-	4700	µF	
	Vo = 12 V		22	-	470	µF	
Transient Response							
ΔV 25%~50% of Max Load		Test conditions: di/dt = 0.1 A/µs, Vin = 48 V, with a 1 µF ceramic capacitor and a Tantalum capacitor (refer to the min. output capacitance above for each output) at the output.	-	220	350	mV	
Settling Time	Vo = 5.0 V		-	120	250	us	
ΔV 50%~25% of Max Load			-	220	350	mV	
Settling Time			-	120	250	us	
ΔV 25%~50% of Max Load	Vo = 12 V		-	400	650	mV	
Settling Time			-	150	300	µs	
ΔV 50%~25% of Max Load			-	400	650	mV	
Settling Time			-	150	300	µs	

5. GENERAL SPECIFICATIONS

PARAMETER	DESCRIPTION	MIN	TYP	MAX	UNIT
Efficiency	Vo = 5.0 V	87	90	-	%
	Vo = 12 V	86	89	-	%
Switching Frequency	Vin = 48 V, Io = full load.	540	600	660	kHz
Isolation Capacitance		-	3900	-	pF
MTBF	Calculated Per Bell Core SR-332 (Io = 80% load, Vin = 48 V, Vo = 5 V, Ta = 25 °C)		2,770,832		hours
Output Voltage Trim Range	Vo = 5.0 V	90	-	110	% Vo
	Vo = 12 V	80	-	110	% Vo
Over Temperature Protection		120	-	140	°C
Over Voltage Protection	Test conditions: Vin = 48 V, full load and short the feedback optocoupler.	-	130	160	% Vo
Weight		-	13	-	g
Dimensions (L × W × H)	SMT Package		1.3 × 0.9 × 0.364		inch
			33.02 × 22.86 × 9.24		mm
	Through Hole Package		1.3 × 0.9 × 0.388		inch
			33.02 × 22.86 × 9.85		mm

6. CONTROL SPECIFICATIONS

PARAMETER	DESCRIPTION	MIN	TYP	MAX	UNIT
Signal Low (Unit On)	Active Low	-0.3	-	0.8	V
Signal High (Unit Off)		2.95	-	18	V
Signal Low (Unit Off)	Active High	-0.3	-	0.8	V
Signal High (Unit On)		2.95	-	18	V
Current Sink		0	-	1	mA

7. EFFICIENCY DATA

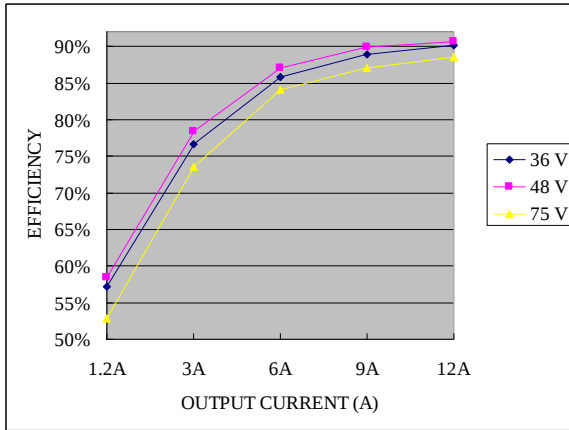


Figure 1. Vo = 5 V

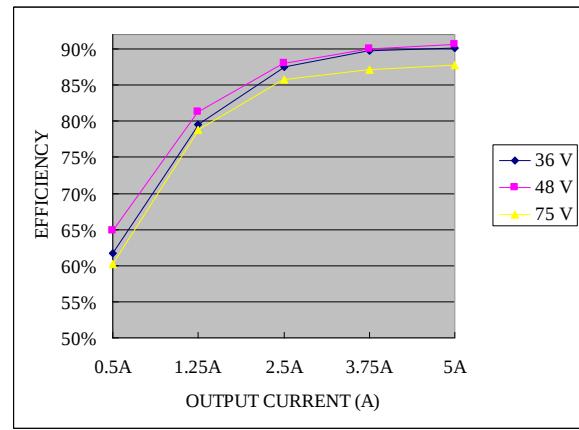


Figure 2. Vo = 12 V

8. OUTPUT TRIM EQUATIONS

Trim Resistor Calculate

Equations for calculating the trim resistor are shown below (Unit: kΩ). The Trim Down resistor should be connected between the Trim pin and Ground pin. The Trim Up resistor should be connected between the Trim pin and the Vout. Only one of the resistors should be used for any given application.

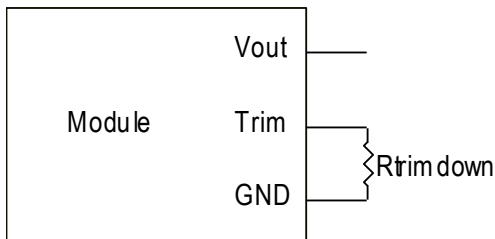


Figure 3. Trim down circuit

$$R_{trimdown} = \frac{511}{|\delta|} - 10.22 [k\Omega]$$

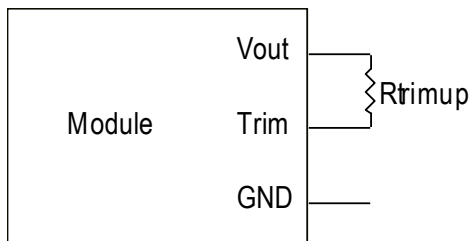


Figure 4. Trim up circuit

$$R_{trimup} = \frac{(100 + \delta) \cdot V_o \cdot 5.11 - 626}{1.225 \cdot \delta} - 10.22 [k\Omega]$$

Note:

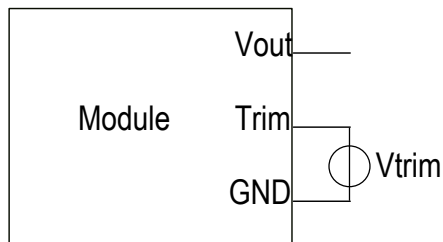
$$\text{delta} = \frac{(V_{o_req} - V_o)}{V_o} \times 100 [\%]$$

V_{o_req} = Desired (trimmed) output voltage [V]

V_o = 5.002 V for 5 V output; V_o = 12.007 V for 12 V output.

Trim Voltage Calculate

Equations for calculating the external trim voltage are shown below (Unit: V).



$$V_{trim} = \frac{2.45}{V_o} \cdot V_{o_req} - 1.225 \text{ [V]}$$

Figure 5. Trim voltage circuit

Note:

V_{o_req} = Desired (trimmed) output voltage [V]

V_o = 5.002 V for 5 V output; V_o = 12.007 V for 12 V output.

9. RIPPLE AND NOISE WAVEFORM

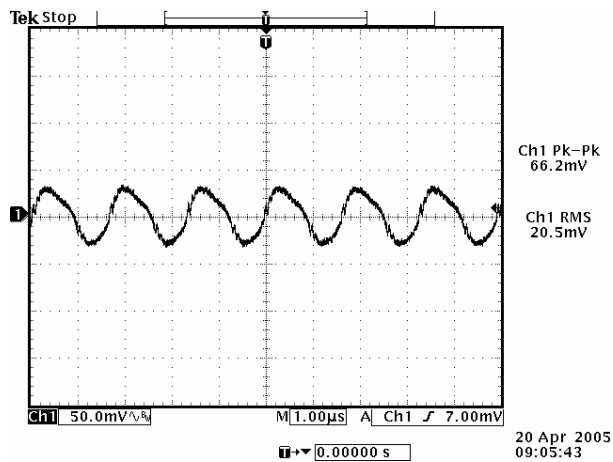


Figure 6. $V_o = 5.0\text{ V}$

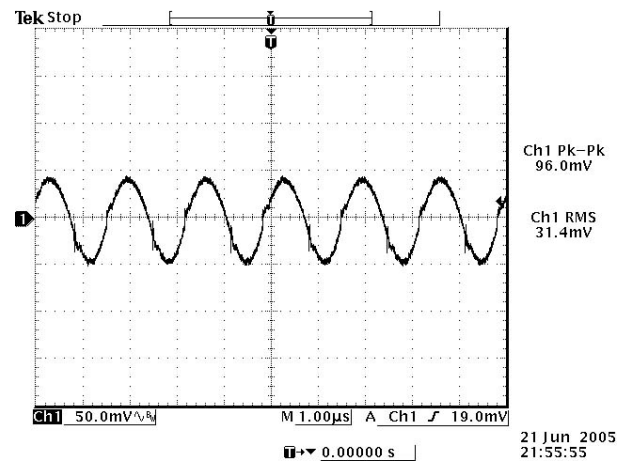


Figure 7. $V_o = 12\text{ V}$

Note: Ripple and Noise at full load, 48 V input, $T_a = 25\text{ }^{\circ}\text{C}$.

- 1) For $V_o = 5.0\text{ V}$, with a $1\text{ }\mu\text{F}$ ceramic capacitor and a $100\text{ }\mu\text{F}$ tantalum cap at the output.
- 2) For $V_o = 12\text{ V}$, with a $1\text{ }\mu\text{F}$ ceramic capacitor and a $22\text{ }\mu\text{F}$ tantalum cap at the output.

10. TRANSIENT RESPONSE WAVEFORMS

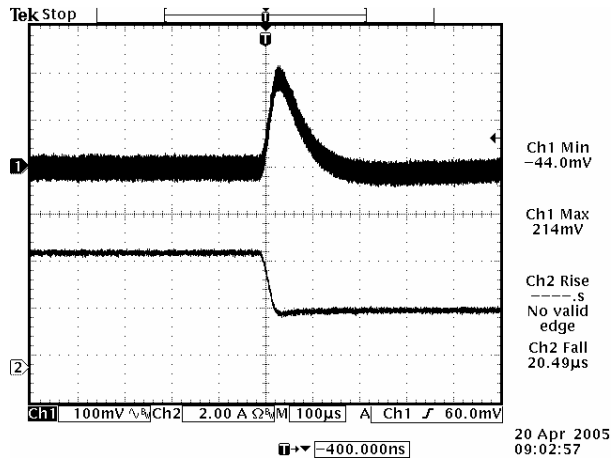


Figure 8. $V_o = 5\text{ V}$, 50% to 25% Load Transients

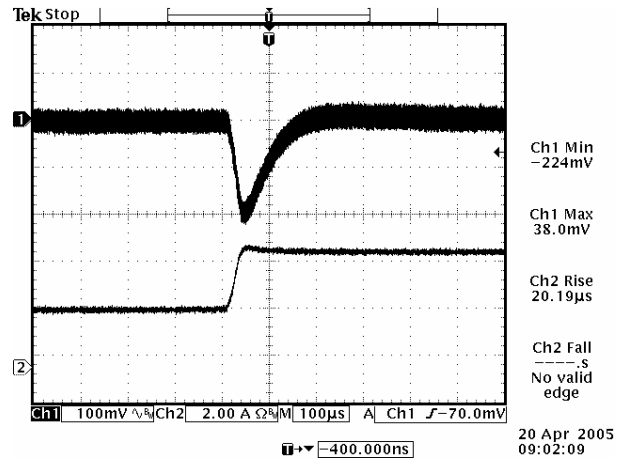


Figure 9. $V_o = 5\text{ V}$, 25% to 50% Load Transients

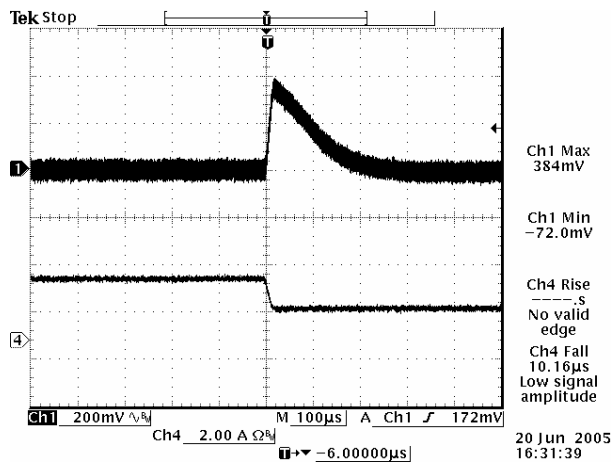


Figure 10. $V_o = 12\text{ V}$, 50% to 25% Load Transients

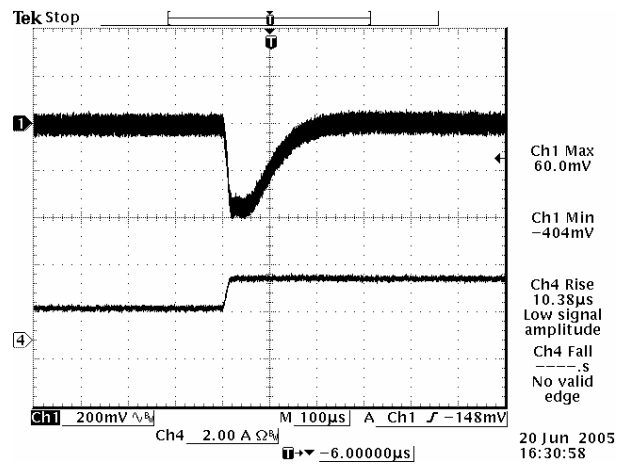


Figure 11. $V_o = 12\text{ V}$, 25% to 50% Load Transients

Note: Transients Response at $V_{in} = 48\text{ V}$, $di/dt = 0.1\text{ A/us}$, $T_a = 25^\circ\text{C}$.

- 1) For $V_o = 5.0\text{ V}$, with a $1\text{ }\mu\text{F}$ ceramic capacitor and a $100\text{ }\mu\text{F}$ tantalum cap at the output.
- 2) For $V_o = 12\text{ V}$, with a $1\text{ }\mu\text{F}$ ceramic capacitor and a $22\text{ }\mu\text{F}$ tantalum cap at the output.

11. THERMAL DERATING CURVE

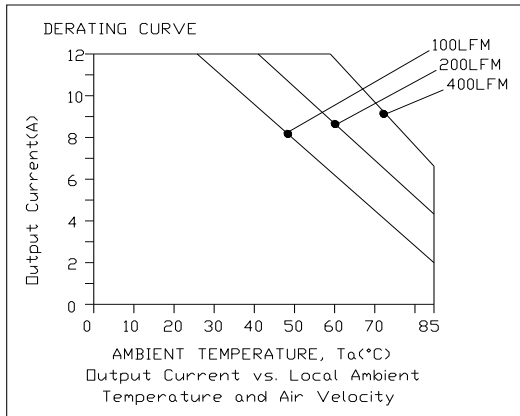


Figure 12. $V_{in} = 36\text{ V}$, $V_o = 5.0\text{ V}$

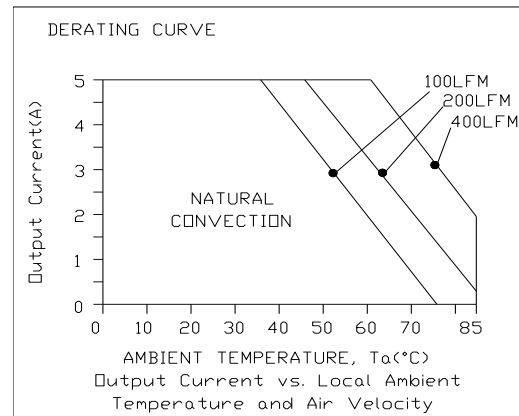


Figure 13. $V_{in} = 36\text{ V}$, $V_o = 12\text{ V}$

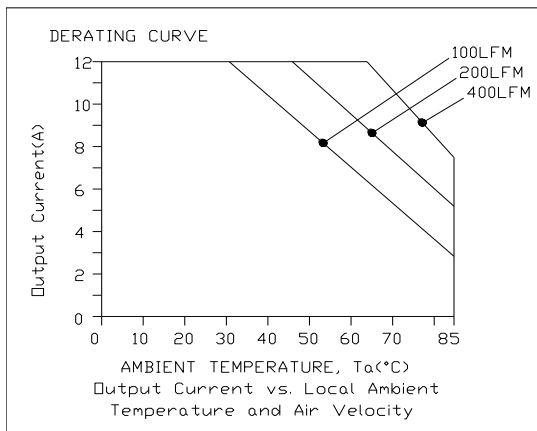


Figure 14. $V_{in} = 48\text{ V}$, $V_o = 5.0\text{ V}$

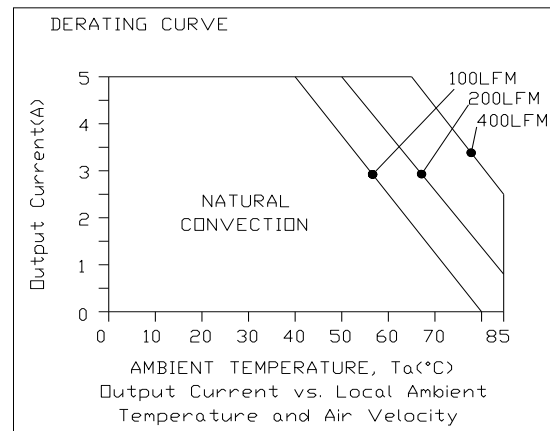


Figure 15. $V_{in} = 48\text{ V}$, $V_o = 12\text{ V}$

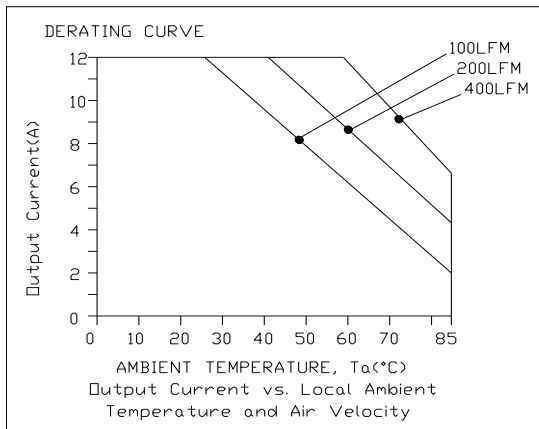


Figure 16. $V_{in} = 75\text{ V}$, $V_o = 5.0\text{ V}$

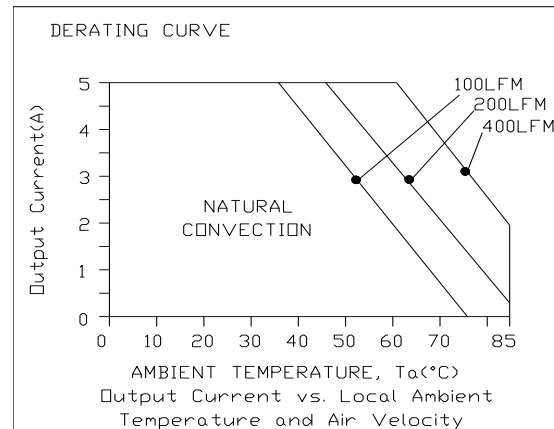


Figure 17. $V_{in} = 75\text{ V}$, $V_o = 12\text{ V}$

12. SOLDERING INFORMATION

The SRSB-50T05/12xy modules are designed to be compatible with reflow soldering process. The suggested Pb-free solder paste is Sn/Ag/Cu (SAC). The recommended reflow profile using Sn/Ag/Cu solder is shown in the following. Recommended reflow peak temperature is 245°C while the part can withstand peak temperature of 260°C maximum for 10 seconds. This profile should be used only as a guideline. Many other factors influence the success of SMT reflow soldering. Since your production environment may differ, please thoroughly review these guidelines with your process engineers.

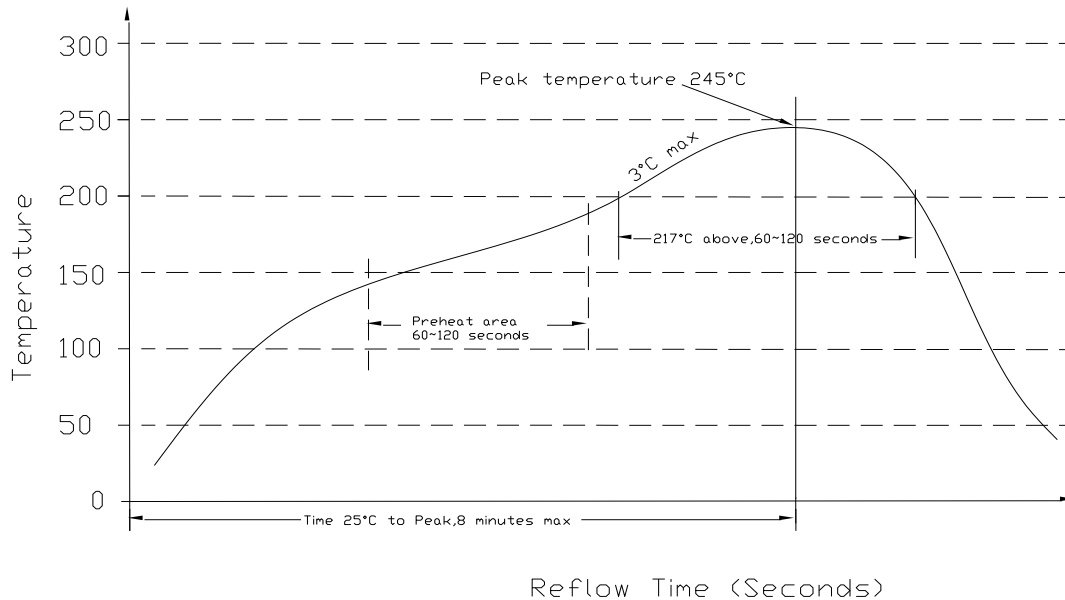


Figure 18. Soldering information

13. MSL RATING

The SRSB-50T05/12xy modules have a MSL rating of 3.

14. STORAGE AND HANDLING

The SRSB-50T05/12xy modules are designed to be compatible with J-STD-033 Rev: A (Handling, Packing, Shipping and Use of Moisture /Reflow Sensitive surface Mount devices). Moisture barrier bags (MBB) with desiccant are applied. The recommended storage environment and handling procedure is detailed in J-STD-033.

15. PRE-BAKING

This component has been designed, handled, and packaged ready for pb-free reflow soldering. If the assembly shop follows J-STD-033 guidelines, no pre-bake of this component is required before being reflowed to a PCB. However, if the J-STD-033 guidelines are not followed by the assembler, Bel recommends that the modules should be pre-baked @ 120~125°C for a minimum of 4 hours (preferably 24 hours) before reflow soldering.

16. MECHANICAL DIMENSIONS

SRSB-50TxxxG/H OUTLINE

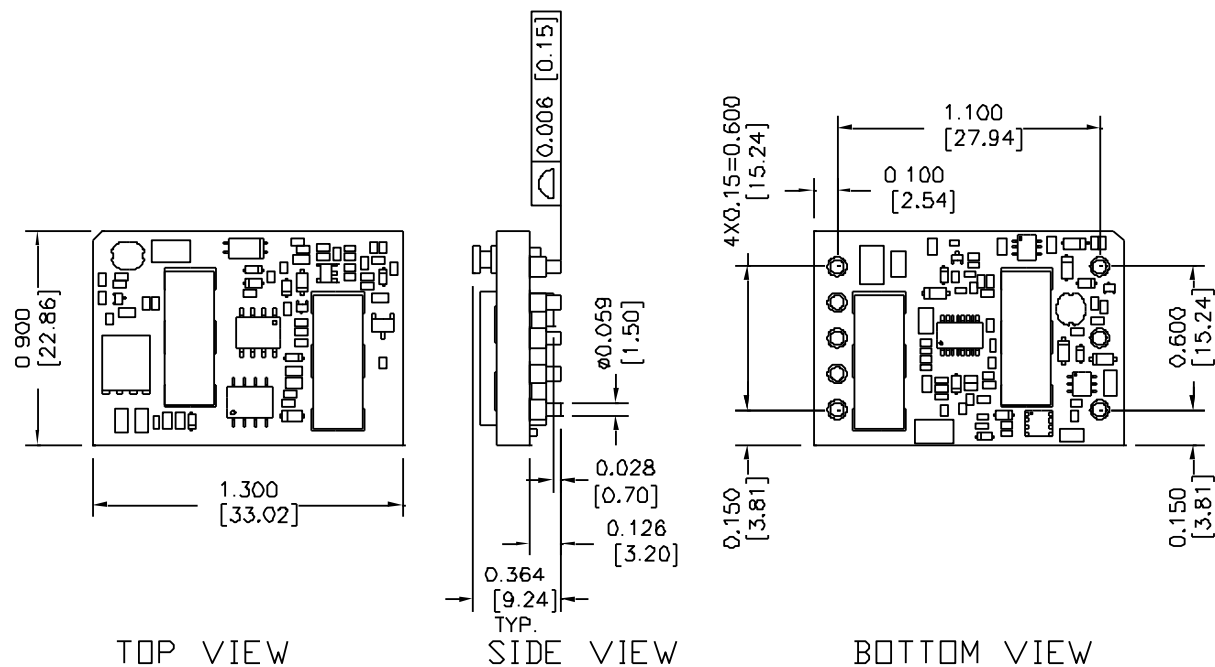


Figure 19. SRSB-50TxxxG/H Outline

Note:

- 1) All Pins: Material - Copper Alloy;
Finish – 3 micro inches minimum Gold over 50 micro inches minimum Nickel plate.
- 2) Un-dimensioned components are shown for visual reference only.
- 3) All dimensions in inch [mm]; Tolerances: x.xx +/-0.02 inch [0.51 mm], x.xxx +/-0.010 inch [0.25 mm] unless otherwise stated

SRSB-50TxxxG/H PIN DEFINITIONS

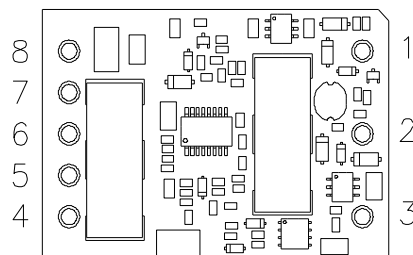
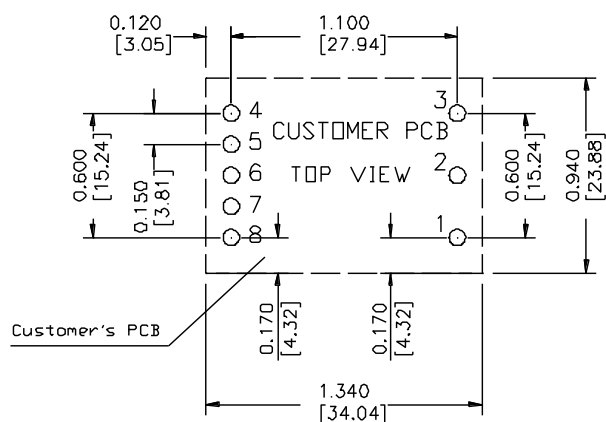


Figure 20. SRSB-50TxxxG/H Pins

PIN	FUNCTION	PIN	FUNCTION
1	Vin (+)	5	SENSE (-)
2	Remote On/Off	6	TRIM
3	Vin (-)	7	SENSE (+)
4	Vout (-)	8	Vout (+)

SRSB-50TxxxG/H RECOMMENDED PAD LAYOUT

RECOMMENDED PCB PAD LAYOUT



Recommended Surface Mount Pads
 Min. $\varnothing 0.080''$ [2.03]
 Max. $\varnothing 0.092''$ [2.34]

Figure 21. SRSB-50TxxxG/H Recommended pad layout

SRSB-50TxxxR/S OUTLINE

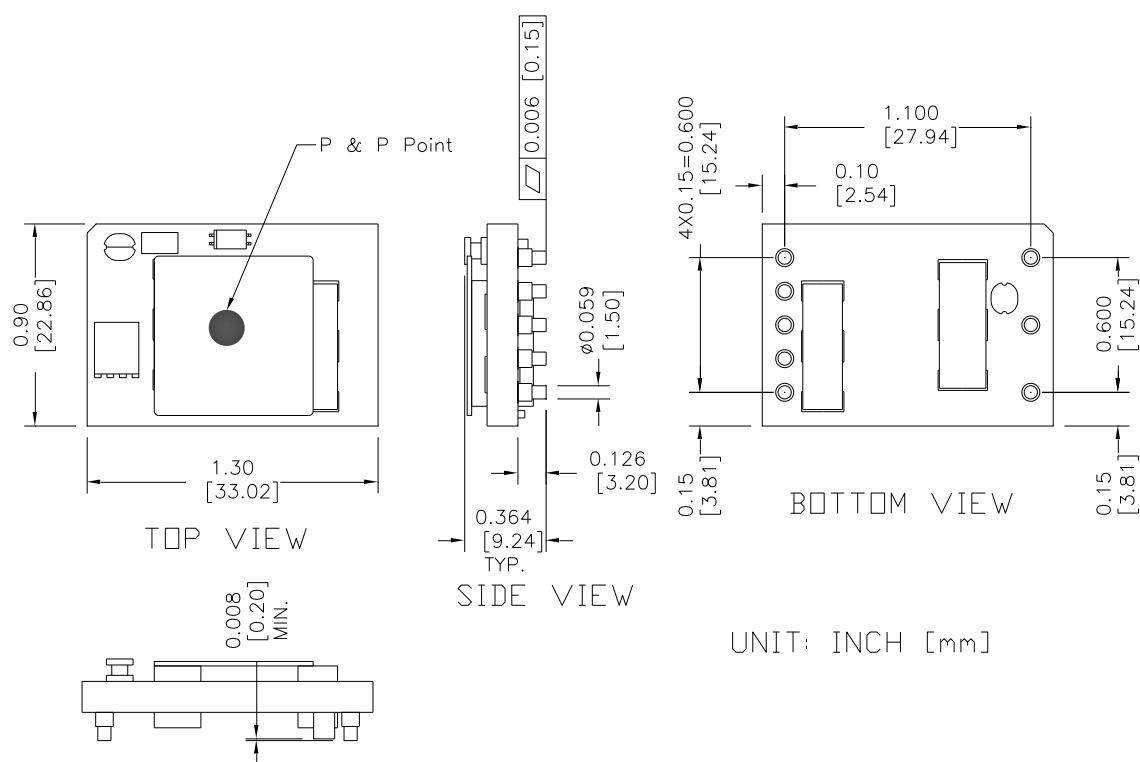


Figure 22. SRSB-50TxxxR/S Outline

Note: These parts are not however compatible with the higher temperatures associated with lead free solder processes and must be soldered using a reflow profile with a peak temperature of no more than 245 °C.

Note:

- 1) All Pins: Material - Copper Alloy;
Finish – 3 micro inches minimum Gold over 50 micro inches minimum Nickel plate.
- 2) Un-dimensioned components are shown for visual reference only.
- 3) All dimensions in inch [mm]; Tolerances: x.xx +/-0.02 inch [0.51 mm], x.xxx +/-0.010 inch [0.25 mm], unless otherwise stated.

Diagram illustrating the layout of a 16-pin connector. The pins are arranged in two rows of 8 pins each. The left row is numbered 8 down to 4, and the right row is numbered 1 down to 3. A central rectangular area is marked with a dashed border.

Figure 23. SRSB-50TxxxR/S Pins

PIN	FUNCTION	PIN	FUNCTION
1	Vin (+)	5	SENSE (-)
2	Remote On/Off	6	TRIM
3	Vin (-)	7	SENSE (+)
4	Vout (-)	8	Vout (+)

Figure 1: Top view of a customer PCB showing dimensions in inches and millimeters. The PCB is rectangular with a central area labeled "CUSTOMER PCB TOP VIEW". Dimensions include: 0.12 [3.05] (top left), 1.100 [27.94] (top), 0.600 [15.24] (left), 0.150 [3.81] (left), 0.600 [15.24] (right), 0.94 [23.88] (right), 1.34 [34.04] (bottom), 0.17 [4.32] (bottom), and 0.17 [4.32] (bottom). Pin numbers 1 through 8 are indicated around the perimeter.

Figure 24. SRSB-50TxxxR/S Recommended pad layout

MECHANICAL DRAWING OF THE PCB (UNIT: INCH [mm])

TOP VIEW:

- Overall Width: 0.900 [22.86]
- Overall Length: 1.300 [33.02]

SIDE VIEW:

- Top Thickness: 0.388 [9.85] MAX.
- Mounting Pad Thickness: 0.140 [3.56]
- Pad Thickness: 0.150 [3.81]
- Pad Thickness: 0.040 [1.02] Typ.6
- Bottom Thickness: 0.062 [1.57] Typ.2

BOTTOM VIEW:

- Overall Width: 0.600 [15.24]
- Mounting Pad Thickness: 0.150 [3.81]
- Pad Thickness: 0.100 [2.54]
- Overall Length: 1.100 [27.94]
- Pad Thickness: 0.150 [3.81]
- Mounting Pad Thickness: 0.300 [7.62]
- Pad Thickness: 0.300 [7.62]

Note: These parts are not however compatible with the higher temperatures associated with lead free solder processes and must be soldered using a reflow profile with a peak temperature of no more than 245 °C.

1) All Pins: Material - Copper Alloy;

2) Un-dimensioned components are shown for visual reference only.

3) All dimensions in inch [mm]; Tolerances: x.xx +/-0.02 inch [0.51 mm], x.xxx +/-0.010 inch [0.25 mm]. unless otherwise stated.

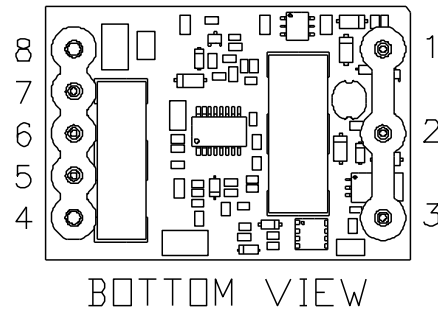
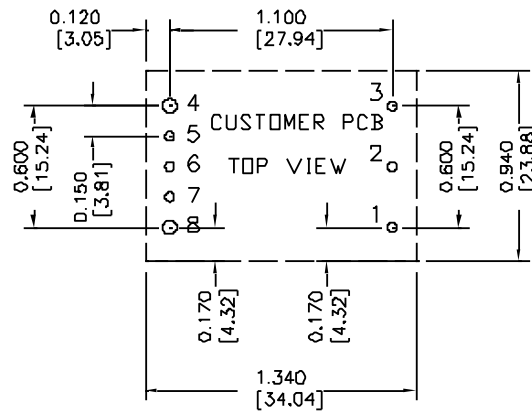
0RSB-50TxxxG/H PIN DEFINITIONS

Figure 26. 0RSB-50TxxxG/H Pins

PIN	FUNCTION	PIN	FUNCTION
1	Vin (+)	5	SENSE (-)
2	Remote On/Off	6	TRIM
3	Vin (-)	7	SENSE (+)
4	Vout (-)	8	Vout (+)

0RSB-50TxxxG/H RECOMMENDED PAD LAYOUT**RECOMMENDED PCB PAD LAYOUT**

HOLE SIZE: 1-3, 5-7 $\varnothing 0.047$ [1.19],
 4,8 $\varnothing 0.07$ [1.78]
 PAD SIZE: 1-3, 5-7 $\varnothing 0.08$ [2.03]
 4,8 $\varnothing 0.10$ [2.54]

Figure 27. 0RSB-50TxxxG/H Recommended pad layout

17. PACKAGING INFORMATION

SRSB-50TxxxR/S

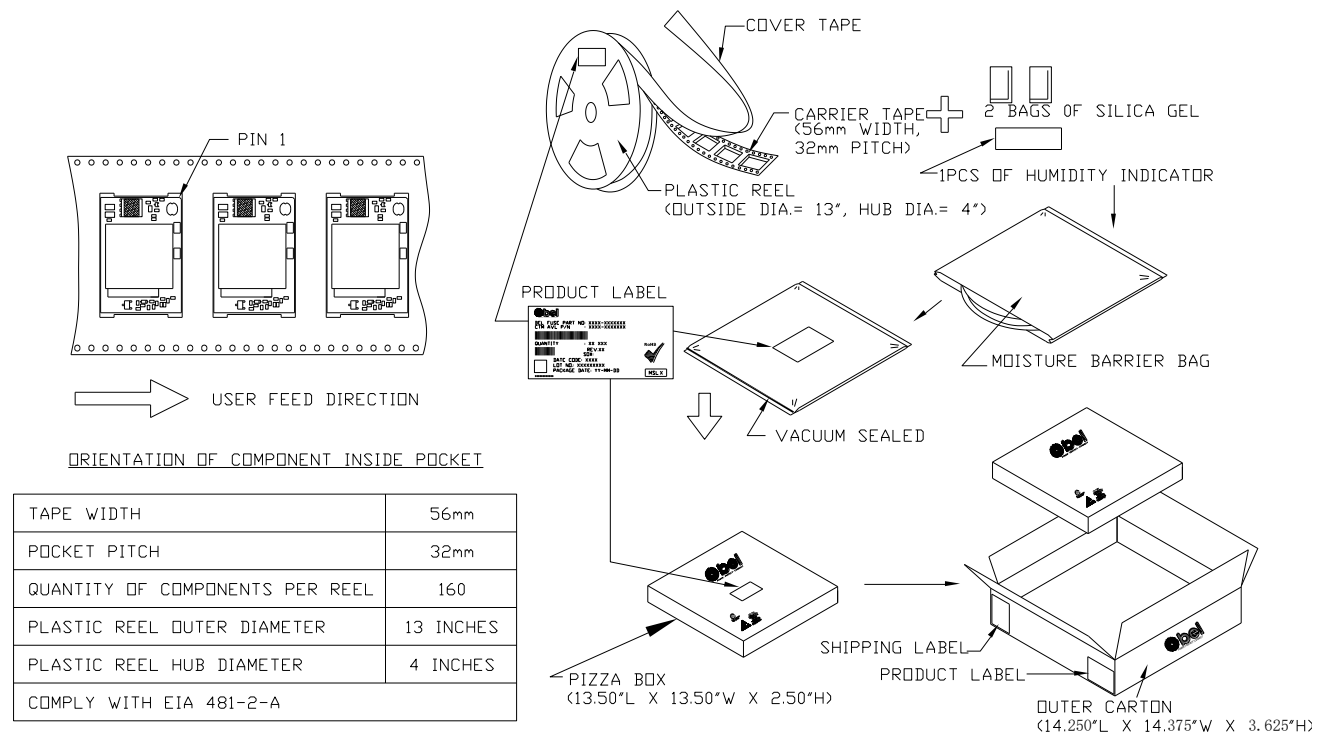


Figure 28. SRSB-50TxxxR/S packaging information

xRSB-50TxxxG/H

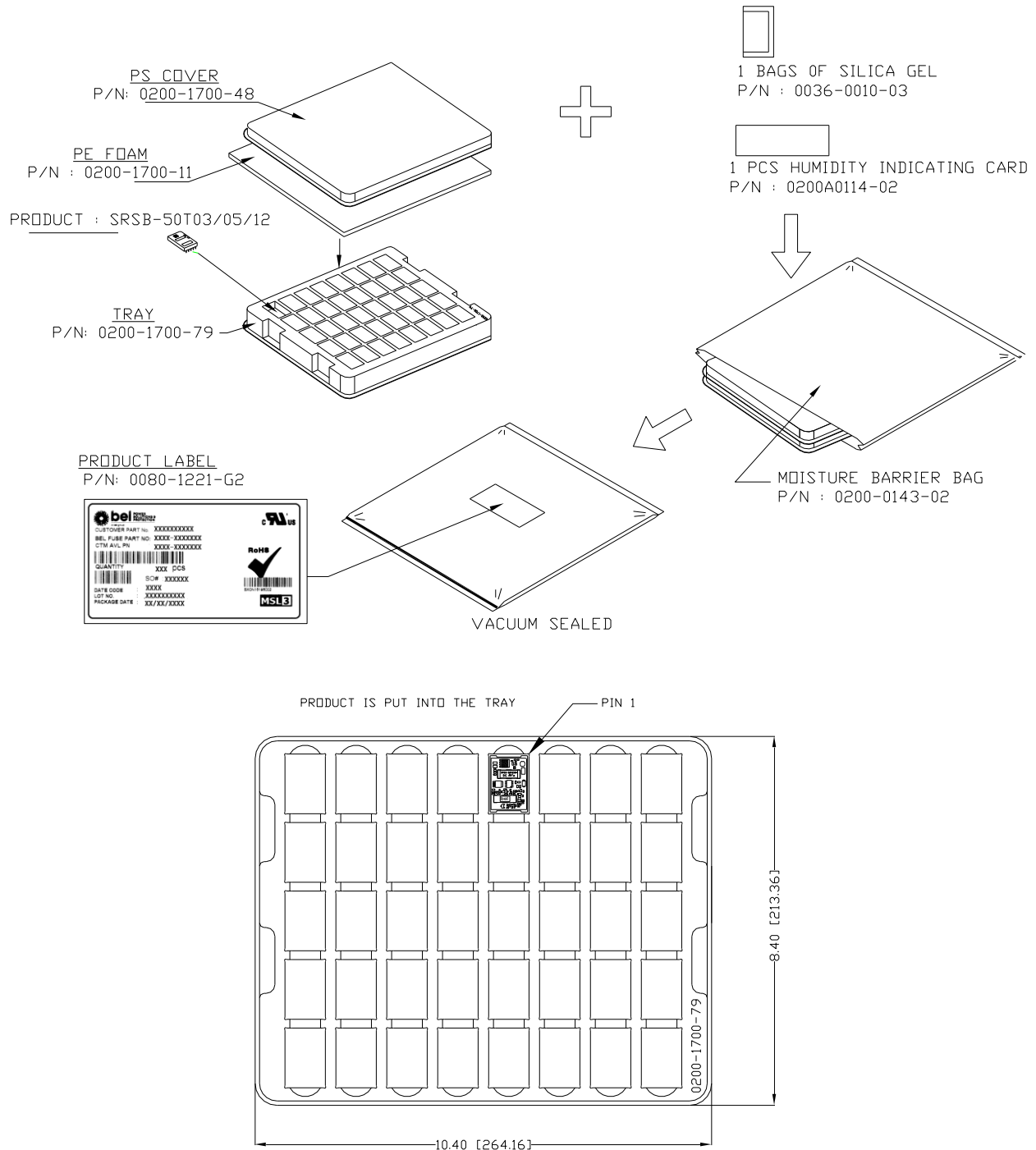


Figure 29. xRSB-50TxxxG/H packaging information

18. REVISION HISTORY

DATE	REVISION	CHANGES DETAIL	APPROVAL
2010-04-12	F	Update the 0RSB-50T series product height from 0.378" to 0.388".	J.Fan
2010-11-17	G	Add Derating Curve under 36Vin, 75Vin at 12V output.	JZ.Wang
2011-05-17	H	Add trim equation for external voltage trim.	JZ.Wang
2011-08-25	I	Update the reflow solder temperature.	HL.Lu
2011-11-01	J	Add thermal derating curve for 36Vin and 75Vin.	JZ.Wang
2012-07-04	K	Adding the 7C-III compliance suFfix statement.	JZ.Wang
2016-09-12	AL	Update form.	J.Yan
2017-03-03	AM	Update part number explanation, mechanical dimensions, packaging information	J.Yan
2021-06-08	AN	Delete xRSB-50TV5x, xRSB-50TV8x, xRSB-50T02x, xRSB-50T03x. Add object ID. Update safety certificate.	XF.Jiang

For more information on these products consult: tech.support@psbel.com

NUCLEAR AND MEDICAL APPLICATIONS - Products are not designed or intended for use as critical components in life support systems, equipment used in hazardous environments, or nuclear control systems.

TECHNICAL REVISIONS - The appearance of products, including safety agency certifications pictured on labels, may change depending on the date manufactured. Specifications are subject to change without notice.



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